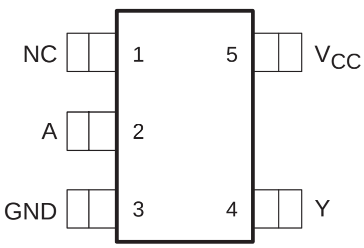
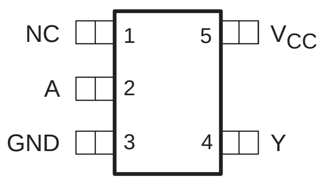
- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Low Static-Power Consumption; I_{CC} = 0.9 μA Max
- Low Dynamic-Power Consumption; C_{pd} = 4.1 pF Typ at 3.3 V
- Low Input Capacitance; C_i = 1.5 pF Typ
- Low Noise − Overshoot and Undershoot <10% of V_{CC}
- I_{off} Supports Partial-Power-Down Mode Operation
- Input Hysteresis Allows Slow Input Transition and Better Switching Noise Immunity at the Input (V_{hys} = 250 mV Typ at 3.3 V)
- Wide Operating V_{CC} Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- t_{pd} = 3.8 ns Max at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- ESD Protection Exceeds ±5000 V With Human-Body Model

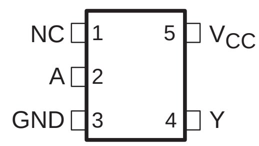
DBV PACKAGE (TOP VIEW)



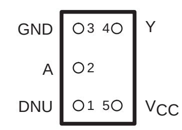
DCK PACKAGE (TOP VIEW)



DRL PACKAGE (TOP VIEW)



YEP OR YZP PACKAGE (BOTTOM VIEW)

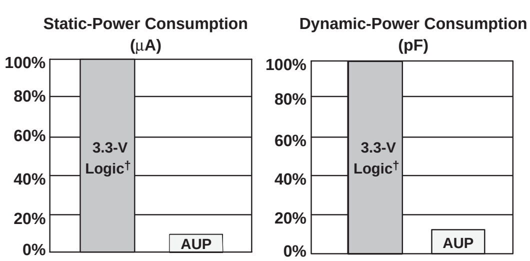


DNU – Do not use

See mechanical drawings for dimensions.

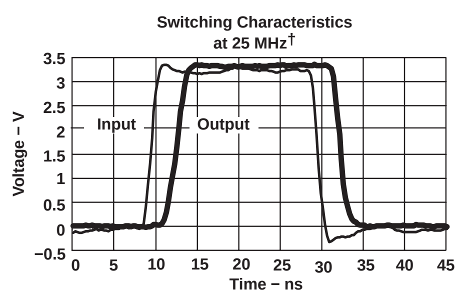
description/ordering information

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static and dynamic power consumption across the entire V_{CC} range of 0.8 V to 3.6 V resulting in an increased battery life. This product also maintains excellent signal integrity (see Figures 1 and 2).



† Single, dual, and triple gates

Figure 1. AUP − The Lowest-Power Family



† AUP1G08 data at C_L = 15 pF

Figure 2. Excellent Signal Integrity

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar and NanoFree are trademarks of Texas Instruments.

description/ordering information (continued)

This single buffer gate performs the Boolean function Y = A in positive logic.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
−40°C to 85°C	NanoStar™ − WCSP (DSBGA) 0.23-mm Large Bump − YEP	Tape and reel	SN74AUP1G34YEPR PACKAGE PREVIEW	_ _ _H9_
	NanoFree™ − WCSP (DSBGA) 0.23-mm Large Bump − YZP (Pb-free)	Tape and reel	SN74AUP1G34YZPR	
	SOT (SOT-23) − DBV	Tape and reel	SN74AUP1G34DBVR	H34_
	SOT (SC-70) − DCK	Tape and reel	SN74AUP1G34DCKR	H9_
	SOT (SOT-553) − DRL	Reel of 4000	SN74AUP1G34DRLR	H9_

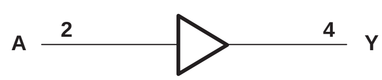
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ DBV/DCK/DRL: The actual top-side marking has one additional character that designates the assembly/test site.
YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

FUNCTION TABLE

INPUT A	OUTPUT Y
H	H
L	L

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	−0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	−0.5 V to 4.6 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	−0.5 V to 4.6 V
Output voltage range in the high or low state, V_O (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0)	−50 mA
Output clamp current, I_{OK} (V_O < 0)	−50 mA
Continuous output current, I_O	±20 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
DRL package	142°C/W
YEP/YZP package	132°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		0.8	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 0.8 V	V_{CC}		V
		V_{CC} = 1.1 V to 1.95 V	$0.65 \times V_{CC}$		
		V_{CC} = 2.3 V to 2.7 V	1.6		
		V_{CC} = 3 V to 3.6 V	2		
V_{IL}	Low-level input voltage	V_{CC} = 0.8 V		0	V
		V_{CC} = 1.1 V to 1.95 V		$0.35 \times V_{CC}$	
		V_{CC} = 2.3 V to 2.7 V		0.7	
		V_{CC} = 3 V to 3.6 V		0.9	
V_I	Input voltage		0	3.6	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}†	High-level output current	V_{CC} = 0.8 V		−20	μA
		V_{CC} = 1.1 V		−1.1	mA
		V_{CC} = 1.4 V		−1.7	
		V_{CC} = 1.65 V		−1.9	
		V_{CC} = 2.3 V		−3.1	
		V_{CC} = 3 V		−4	
I_{OL}†	Low-level output current	V_{CC} = 0.8 V		20	μA
		V_{CC} = 1.1 V		1.1	mA
		V_{CC} = 1.4 V		1.7	
		V_{CC} = 1.65 V		1.9	
		V_{CC} = 2.3 V		3.1	
		V_{CC} = 3 V		4	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 0.8 V to 3.6 V		200	ns/V
T_A	Operating free-air temperature		−40	85	°C

† Defined by the signal integrity requirements and design goal priorities

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	T_A = 25°C MIN	TYP	MAX	T_A = −40°C TO 85°C MIN	MAX	UNIT
V_{OH}		I_{OH} = −20 μA		0.8 V to 3.6 V	V_{CC} − 0.1			V_{CC} − 0.1		V
		I_{OH} = −1.1 mA		1.1 V	0.75 × V_{CC}			0.7 × V_{CC}		
		I_{OH} = −1.7 mA		1.4 V	1.11			1.03		
		I_{OH} = −1.9 mA		1.65 V	1.32			1.3		
		I_{OH} = −2.3 mA		2.3 V	2.05			1.97		
		I_{OH} = −3.1 mA			1.9			1.85		
		I_{OH} = −2.7 mA		3 V	2.72			2.67		
		I_{OH} = −4 mA			2.6			2.55		
V_{OL}		I_{OL} = 20 μA		0.8 V to 3.6 V			0.1		0.1	V
		I_{OL} = 1.1 mA		1.1 V			0.3 × V_{CC}		0.3 × V_{CC}	
		I_{OL} = 1.7 mA		1.4 V			0.31		0.37	
		I_{OL} = 1.9 mA		1.65 V			0.31		0.35	
		I_{OL} = 2.3 mA		2.3 V			0.31		0.33	
		I_{OL} = 3.1 mA					0.44		0.45	
		I_{OL} = 2.7 mA		3 V			0.31		0.33	
		I_{OL} = 4 mA					0.44		0.45	
I_I	A input	V_I = GND to 3.6 V		0 V to 3.6 V			0.1		0.5	μA
I_{off}		V_I or V_O = 0 V to 3.6 V		0 V			0.2		0.6	μA
ΔI_{off}		V_I or V_O = 0 V to 3.6 V		0 V to 0.2 V			0.2		0.6	μA
I_{CC}		V_I = GND or (V_{CC} to 3.6 V)	I_O = 0	0.8 V to 3.6 V			0.5		0.9	μA
ΔI_{CC}		V_I = V_{CC} − 0.6 V	I_O = 0	3.3 V			40		50	μA
C_i		V_I = V_{CC} or GND		0 V		1.5				pF
				3.6 V		1.5				
C_o		V_O = GND		0 V		2.5				pF

switching characteristics over recommended operating free-air temperature range, C_L = 5 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C MIN	TYP	MAX	T_A = −40°C TO 85°C MIN	MAX	UNIT
t_{pd}	A	Y	0.8 V	1.8	14.5	27.4			ns
			1.2 V ± 0.1 V	3	5.6	11.2	0.4	13.9	
			1.5 V ± 0.1 V	2.5	4	7.2	0.7	9.2	
			1.8 V ± 0.15 V	2.2	3.2	6	0.8	7.3	
			2.5 V ± 0.2 V	1.8	2.4	3.9	0.6	5.1	
			3.3 V ± 0.3 V	1.4	2	3.2	0.6	4.1	

switching characteristics over recommended operating free-air temperature range, C_L = 10 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8 V	2.7	16.6	28.2			ns
			1.2 V ± 0.1 V	3.6	6.6	12.7	0.3	15.4	
			1.5 V ± 0.1 V	3	4.8	8.3	1.2	10.3	
			1.8 V ± 0.15 V	2.7	3.9	6.9	1.3	8.3	
			2.5 V ± 0.2 V	2.3	2.9	4.5	1.2	5.8	
			3.3 V ± 0.3 V	2	2.4	3.8	1.1	4.8	

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8 V	5.1	18.6	30.2			ns
			1.2 V ± 0.1 V	4.3	7.5	13.6	1.3	16.5	
			1.5 V ± 0.1 V	3.6	5.5	9	1.9	11.2	
			1.8 V ± 0.15 V	3.2	4.5	7.5	1.9	8.9	
			2.5 V ± 0.2 V	2.6	3.4	5.2	1.7	6.5	
			3.3 V ± 0.3 V	2.3	2.9	4.2	1.5	5	

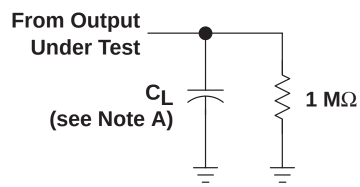
switching characteristics over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8 V	9.9	24.2	36.3			ns
			1.2 V ± 0.1 V	6.3	10.1	16.3	3.6	18.9	
			1.5 V ± 0.1 V	5.1	7.4	11	3.4	13	
			1.8 V ± 0.15 V	4.5	6.1	9.3	3.2	10.6	
			2.5 V ± 0.2 V	3.7	4.7	6.4	2.7	7.8	
			3.3 V ± 0.3 V	3.3	4	5.3	2.5	6.5	

operating characteristics, T_A = 25°C

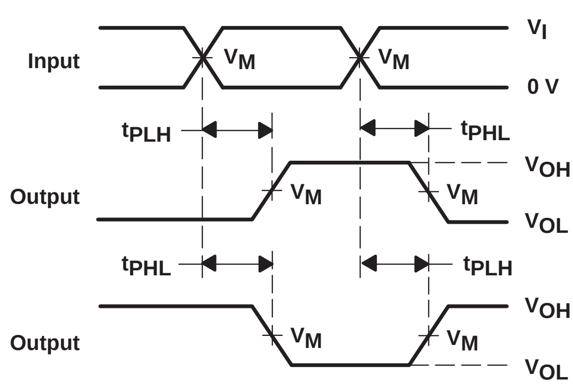
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	0.8 V	3.8	pF
			1.2 V ± 0.1 V	3.8	
			1.5 V ± 0.1 V	3.8	
			1.8 V ± 0.15 V	3.8	
			2.5 V ± 0.2 V	3.9	
			3.3 V ± 0.3 V	4.1	

PARAMETER MEASUREMENT INFORMATION
(Propagation Delays, Setup and Hold Times, and Pulse Width)

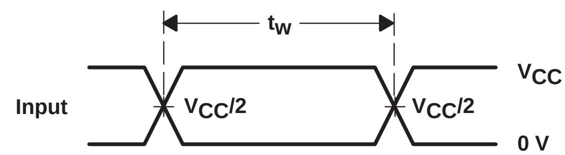


LOAD CIRCUIT

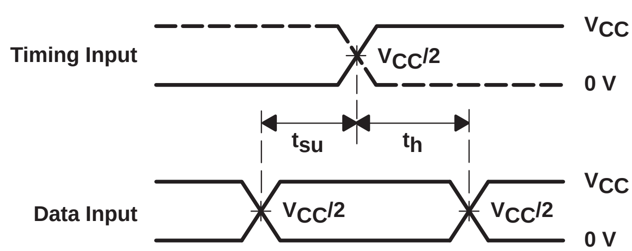
	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION

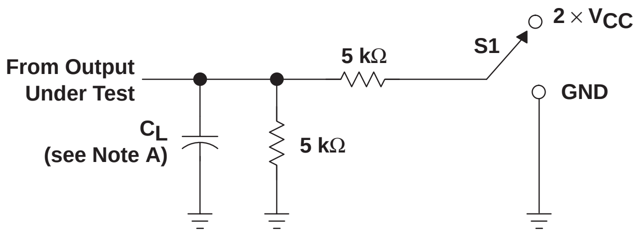


VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

NOTES:
A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f = 3 ns.
C. The outputs are measured one at a time, with one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd}.
E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

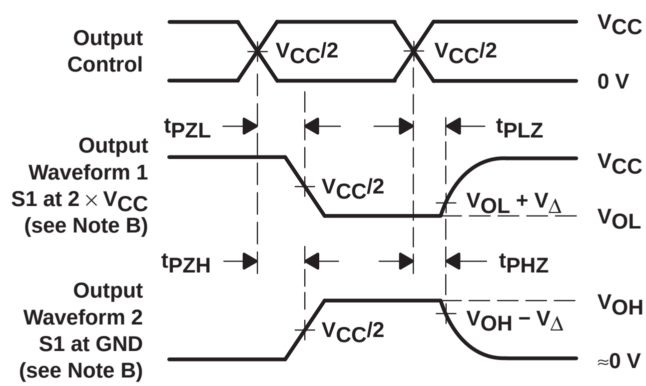
PARAMETER MEASUREMENT INFORMATION (Enable and Disable Times)



LOAD CIRCUIT

TEST	S1
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES:
A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f = 3 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74AUP1G34DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G34DRLR	ACTIVE	SOP	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

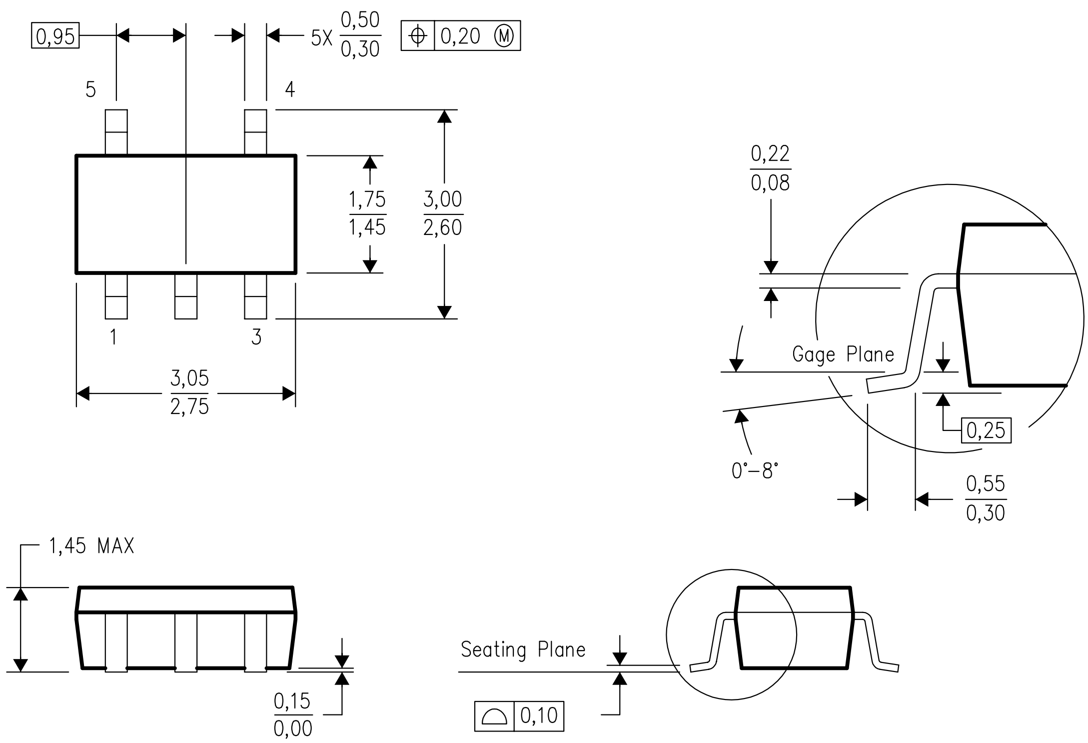
[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

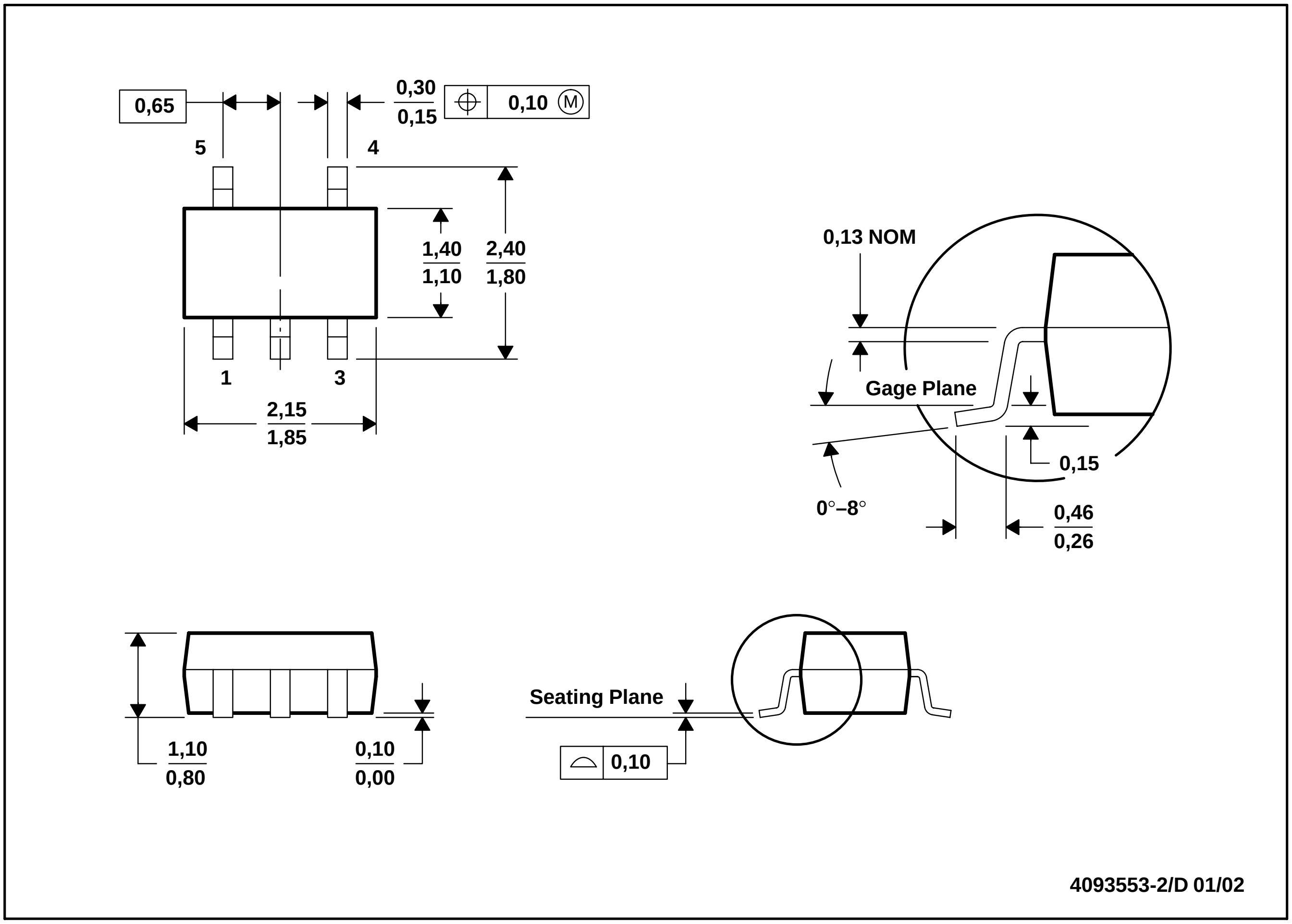
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DBV (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE

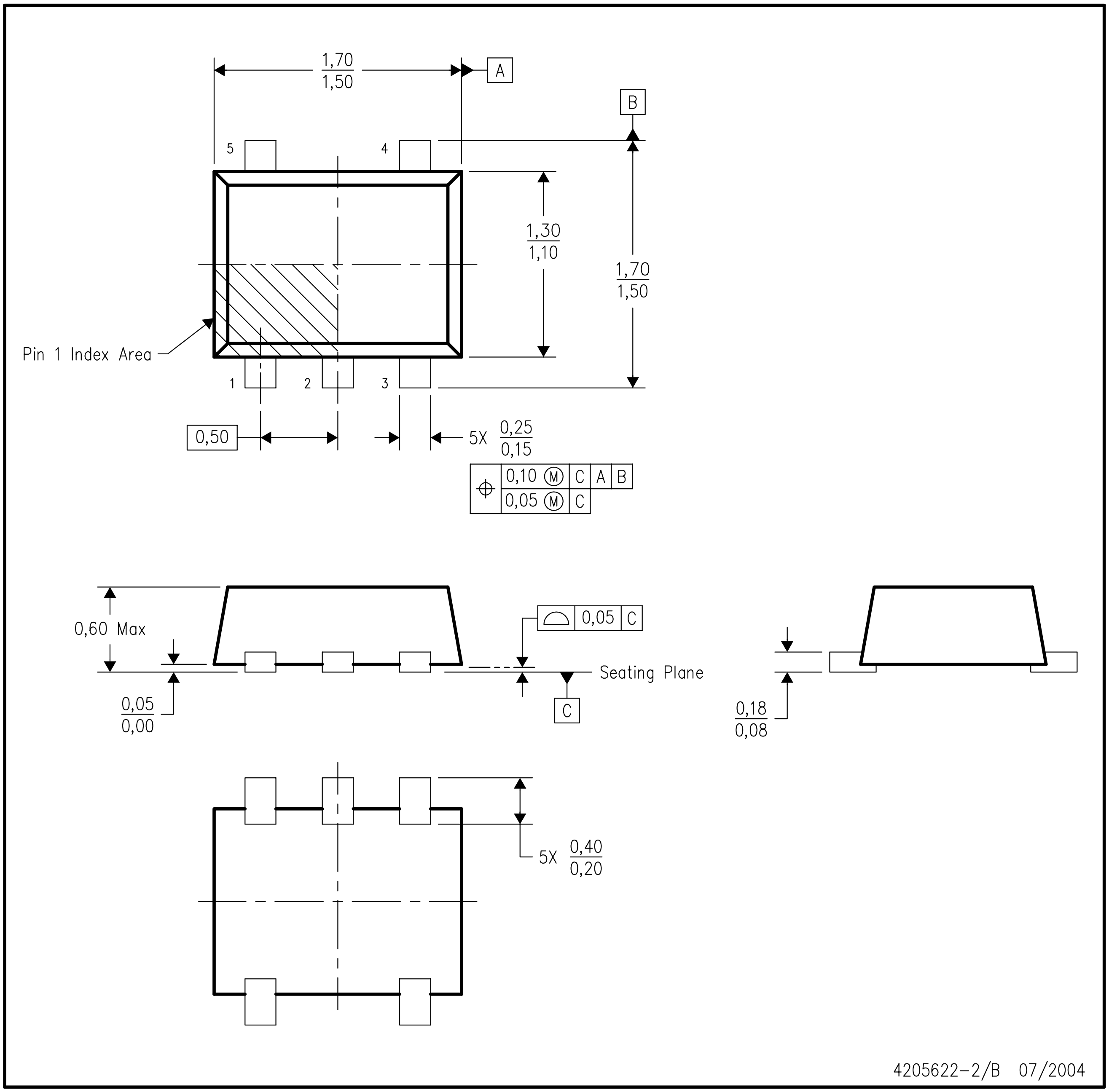


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC MO–178 Variation AA.

DCK (R-PDSO-G5) **PLASTIC SMALL-OUTLINE PACKAGE**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC MO-203



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. JEDEC package registration is pending.

IMPORTANT NOTICE

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		**Applications**	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265